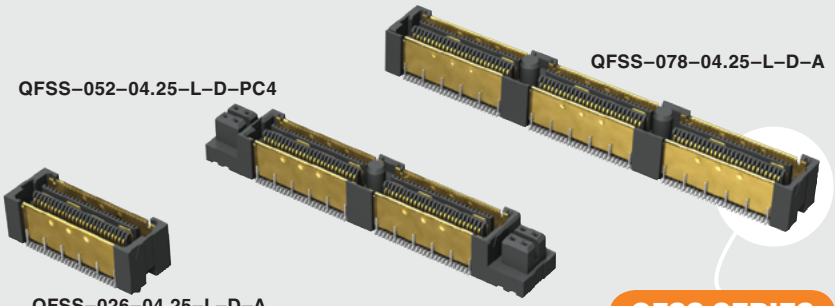
samtec

Q2™



(0.635 mm) .025"

QFSS SERIES

SHIELDED GROUND PLANE SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QFSS

Insulator Material:
Liquid Crystal Polymer
Contact, Ground
Plane & Shield Material:
Phosphor Bronze
Plating:
Au over 50 µ" (1.27 µm) Ni
(Tin on Ground Plane tails)
Voltage Rating:
300 VAC mated with QMSS
Operating Temp:
-55 °C to +125 °C
RoHS Compliant:
Yes

PROCESSING

Lead–Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max (026-078)
Board Stacking:
For applications requiring more than two connectors per board, contact ipg@samtec.com

RECOGNITIONS

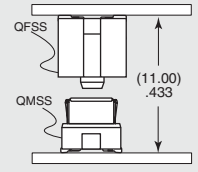
For complete scope of recognitions see www.samtec.com/quality

FILE NO. E111594

ALSO AVAILABLE
(MOQ Required)

- Headers without Alignment Pins
- 8 Power Pins/End
- 4 or 8 Power Pins/End for (2.36 mm) .093" thick board
- Guide Holes
- 64 (-DP) and 104 pins per row

APPLICATION



Notes:
Patented

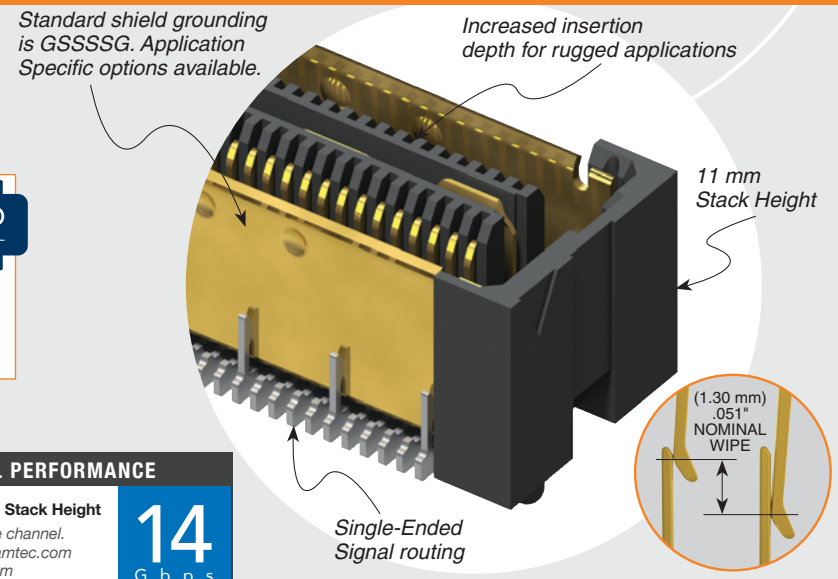
Some lengths, styles and options are non-standard, non-returnable.

Board Mates:
QMSS

Standoffs:
SO

RUGGEDIZED BY SAMTEC

- Increased insertion depth
- Integral guide post



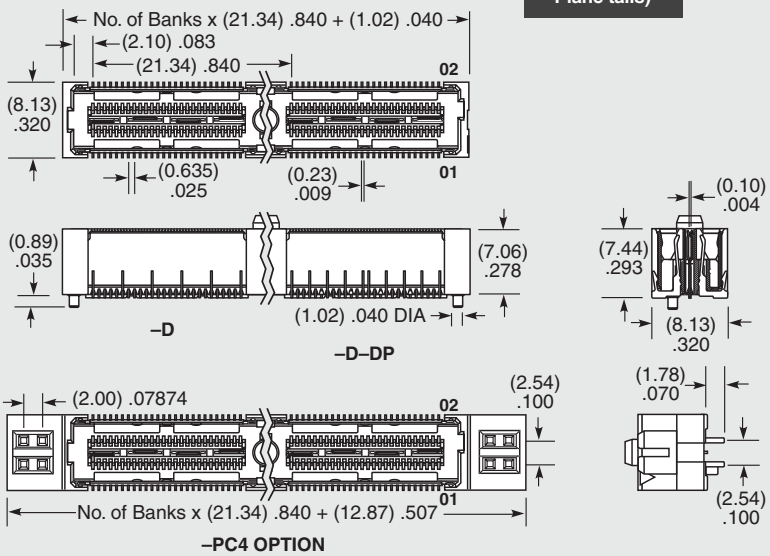
HIGH-SPEED CHANNEL PERFORMANCE

QMSS-DP/QFSS-DP @ 11 mm Mated Stack Height

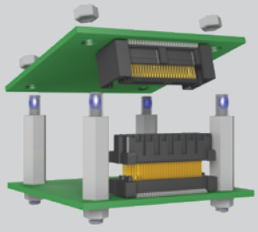
Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

14 Gbps

QFSS	–	PINS PER ROW NO. OF PAIRS	–	04.25	–	PLATING OPTION	–	TYPE	–	A	–	OTHER OPTION
		–026, –052, –078 (52 total pins per bank 40 signals + 12 grounds to shield = –D) **–016, –032, –048** (16 pairs per bank = –D–DP)				**–L** = 10 µ" (0.25 µm) Gold on Signal Pins, Shield and Ground Plane (Tin on Signal Pin tails, and Ground Plane tails)		**–D** = Single-Ended **–D–DP** = Differential Pair				**–PC4** = 4 Power Pins/End (N/A with –A)



OTHER SOLUTIONS



See SO Series for precision machined standoffs.